

N-Channel Enhancement Mode Power MOSFET

Description

The 8205A uses advanced trench technology to provide excellent $R_{\rm DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

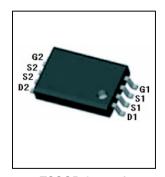
General Features

- $V_{DS} = 19.5V, I_{D} = 6A$
 - $R_{DS(ON)}$ < 37m Ω @ V_{GS} =2.5V
 - $R_{DS(ON)}$ < 27m Ω @ V_{GS} =4.5V
- High Power and current handing capability
- Lead free product is acquired
- Surface Mount Package

Application

- Battery protection
- Load switch
- Power management

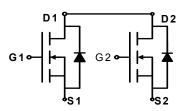
8205A



TSSOP-8 top view



pin Assignment



Schematic diagram

Absolute Maximum Ratings (TA=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	19.5	V	
Gate-Source Voltage	V _{GS}	±10	V	
Drain Current-Continuous	I _D	6	Α	
Drain Current-Pulsed (Note 1)	I _{DM}	25	Α	
Maximum Power Dissipation	P _D	1.5	W	
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$	

Thermal Characteristic

Thermal Resistance, Junction-to-Ambient (Note 2)	R _{θJA}	83	°C/W
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Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	19.5	21		V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =19.5V,V _{GS} =0V			1	μΑ



Gate-Body Leakage Current	I _{GSS}	V _{GS} =±10V,V _{DS} =0V			±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.7	1.2	V
Drain-Source On-State Resistance	В	V _{GS} =4.5V, I _D =4.5A		21	27	mΩ
	R _{DS(ON)}	V _{GS} =2.5V, I _D =3.5A		27	37	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =4.5A		10		S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	- V _{DS} =8V,V _{GS} =0V, - F=1.0MHz		600		PF
Output Capacitance	C _{oss}			330		PF
Reverse Transfer Capacitance	C _{rss}			140		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}	V_{DD} =10V, I_{D} =1A V_{GS} =4.5V, R_{GEN} =6 Ω		10	20	nS
Turn-on Rise Time	t _r			11	25	nS
Turn-Off Delay Time	t _{d(off)}			35	70	nS
Turn-Off Fall Time	t _f			30	60	nS
Total Gate Charge	Qg	V _{DS} =10V,I _D =6A, V _{GS} =4.5V		10	15	nC
Gate-Source Charge	Q_gs			2.3		nC
Gate-Drain Charge	Q_{gd}			1.5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =1.7A		0.75	1.2	V
Diode Forward Current (Note 2)	Is				1.7	Α

Notes:

- $\textbf{1.} \ \textbf{Repetitive Rating: Pulse width limited by maximum junction temperature.}$
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

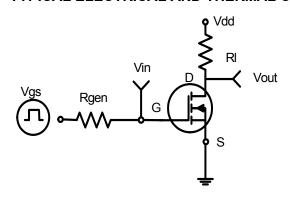


Figure 1:Switching Test Circuit

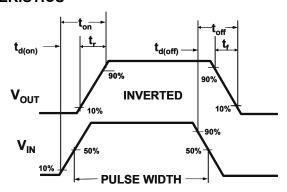


Figure 2:Switching Waveforms

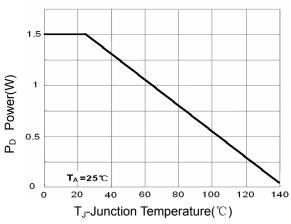


Figure 3 Power Dissipation

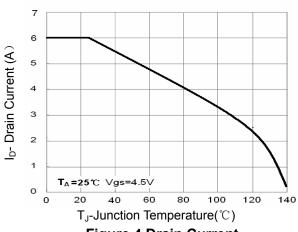


Figure 4 Drain Current

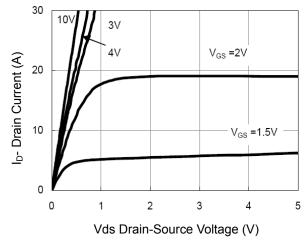


Figure 5 Output CHARACTERISTICS

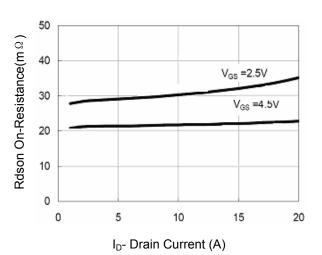


Figure 6 Drain-Source On-Resistance



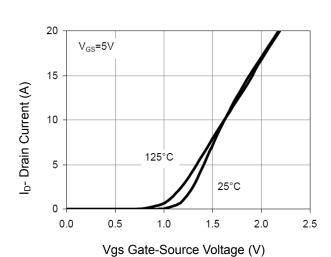
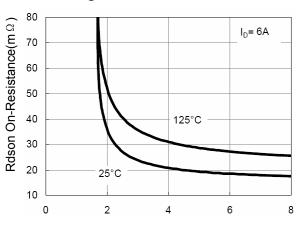


Figure 7 Transfer Characteristics



Vgs Gate-Source Voltage (V) Figure 9 Rdson vs Vgs

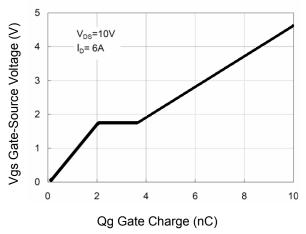
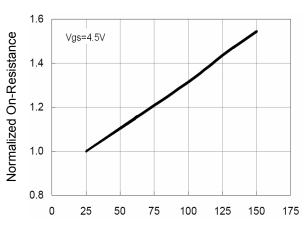
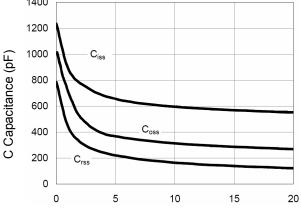


Figure 11 Gate Charge



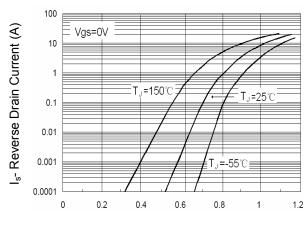
T_J-Junction Temperature(°C)





Vds Drain-Source Voltage (V)

Figure 10 Capacitance vs Vds



Vsd Source-Drain Voltage (V)

Figure 12 Source- Drain Diode Forward



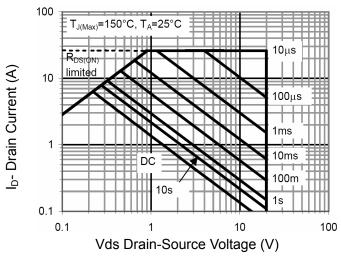


Figure 13 Safe Operation Area

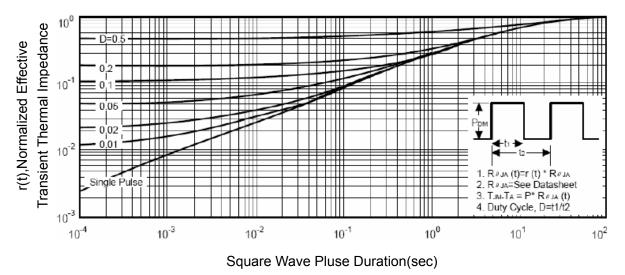


Figure 14 Normalized Maximum Transient Thermal Impedance